

QuickSinter[®]

High metal content paste, redefining sinter technology for power electronics



Pressureless Sinter Pastes

InBAKE

Target applications: Pb replacement in power discretes, die-attach for power devices, RF GaN, and high-power LEDs



InBAKE AgCu

Pressureless silver sinter paste

Features:

- Sinterable in a "reflow-like" profile for small die
- Sinterable to Ag and Cu
- Printable and dispensable

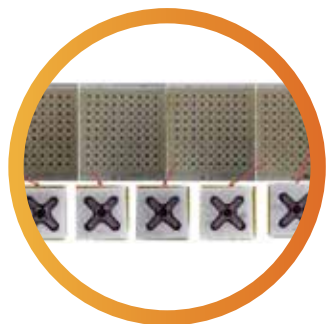


InBAKE MP

Pressureless silver sinter paste

Features:

- Printable and dispensable
- Room temperature storable
- Sinterable to Ag, Au, and Cu

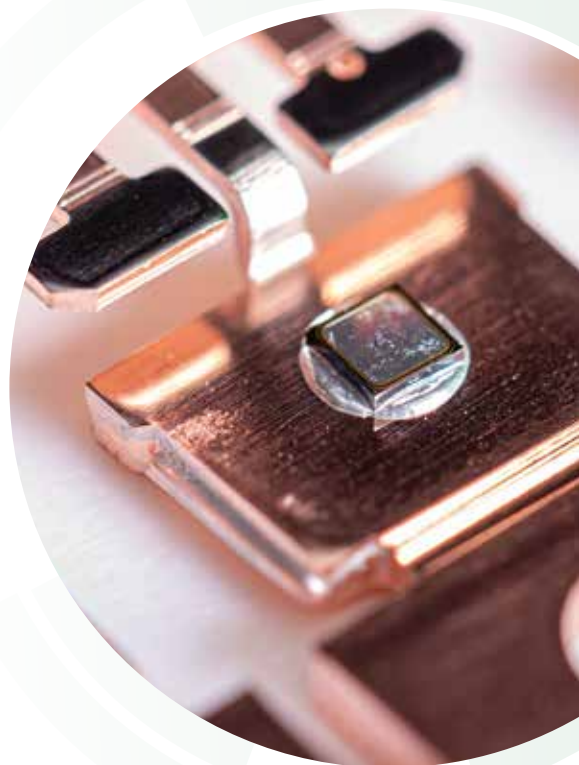


InBAKE 29

Pressureless copper sinter paste

Features:

- Consistent dispense performance
- Can be sintered with or without pressure
- Shear strength >25MPa for pressureless sinter



indium.com/products/silver-sintering



Contact our engineers: askus@indium.com

From One Engineer To Another[®]

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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QuickSinter®

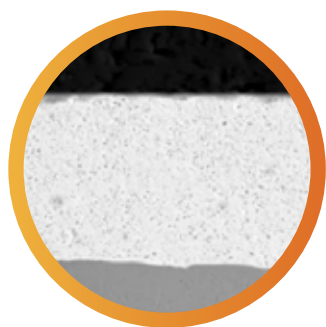
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Pressure Sinter Pastes

InFORCE™

Target applications: Power module die-attach and sintered package-attach to cooler

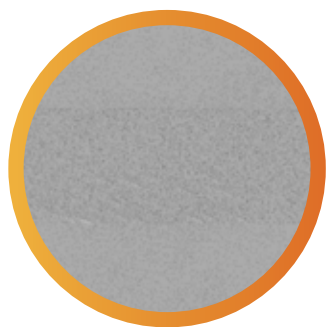
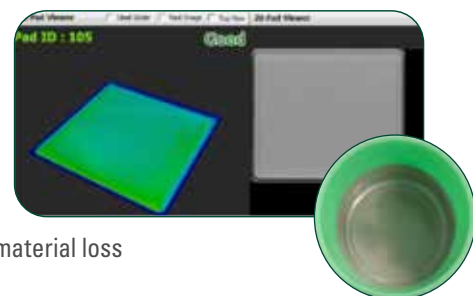


InFORCE™ MF AVAILABLE

Pressure silver sinter paste for die-attach

Features:

- Formulated for printing application. Reduces overprint
- High metal load / low organic content. Fast dry times, less material loss
- Multi finish. Sinters to Ag, Au, or bare Cu
- Suitable for Si IGBT, SiC MOSFET, and GaN HEMT
- Shear strength >50MPa for 5x5 SiC MOSFET



InFORCE™ 29 AVAILABLE

Pressure copper sinter paste

Features:

- Workability – Printable or dispensable
- Sinters to Cu, Ag, and Au
- Sinterable under N₂, vacuum, H₂, forming gas or formic acid
- Shear strength >40MPa
- High metal load / low organic content



InFORCE™ LA IN DEVELOPMENT

Pressure silver sinter paste for large area sintering/package-attach

Features:

- Formulated for large area such as sintered package-attach
- Drying can be done after component placement (wet process)
- Dispense “print like” film deposits (slot nozzle dispensing)

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